SiHG22N60S

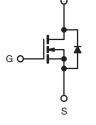




S Series Power MOSFET

PRODUCT SUMMARY					
V_{DS} at T_J max. (V)	650				
R _{DS(on)} max. at 25 °C (Ω)	$V_{GS} = 10 V$	0.190			
Q _g max. (nC)	98				
Q _{gs} (nC)	17				
Q _{gd} (nC)	25				
Configuration	Single				





N-Channel MOSFET

FEATURES

- Generation one
- High E_{AR} capability
- Lower figure-of-merit Ron x Qg
- 100 % avalanche tested
- Ultra low R_{on}
- dV/dt ruggedness
- Ultra low gate charge (Qg)
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

- PFC power supply stages
- Hard switching topologies
- Solar inverters
- UPS
- Motor control
- Lighting
- Server telecom

ORDERING INFORMATION				
Package	TO-247AC			
Lead (Pb)-free	SiHG22N60S-E3			
Lead (Pb)-free and Halogen-free	SiHG22N60S-GE3			

ABSOLUTE MAXIMUM RATINGS ($T_c = 25 \degree C$, unless otherwise noted)							
PARAMETER			SYMBOL	LIMIT	UNIT		
Drain-Source Voltage			V _{DS}	600	V		
Gate-Source Voltage			V _{GS}	± 30	- V		
Continuous Drain Current	V _{GS} at 10 V	T _C = 25 °C T _C = 100 °C	- I _D	22			
Continuous Drain Current	VGS at 10 V	T _C = 100 °C		13	A		
Pulsed Drain Current ^a			I _{DM}	65	1		
Linear Derating Factor		TO-247		2	W/°C		
Single Pulse Avalanche Energy ^b			E _{AS}	690			
Repetitive Avalanche Energy ^a			E _{AR}	25	— mJ		
Maximum Power Dissipation		TO-247	PD	250	W		
Drain-Source Voltage Slope	T _J = 125 °C		dV/dt	37	V/ns		
Reverse Diode dV/dt ^d			uv/di	5.3	7 V/ns		
Operating Junction and Storage Temperature Range			T _J , T _{stg}	-55 to +150	°C		
Soldering Recommendations (Peak Temperature) ^c	for 10 s		-	300			

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature.

b. V_{DD} = 50 V, starting T_J = 25 °C, L = 28.2 mH, R_g = 25 Ω , I_{AS} = 7 A.

c. 1.6 mm from case.

d. $I_{SD} \leq I_D$, dI/dt = 100 A/µs, starting T_J = 25 °C.

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THERMAL RESISTANCE RATINGS						
PARAMETER		SYMBOL	TYP.	MAX.	UNIT	
Maximum Junction-to-Ambient	TO-247	R _{thJA}	-	62	°C/W	
Maximum Junction-to-Case (Drain)	TO-247	R _{thJC}	-	0.5		

PARAMETER	SYMBOL	TES	MIN.	TYP.	MAX.	UNIT	
Static							•
Drain-Source Breakdown Voltage	V _{DS}	V _{GS}	600	-	-	V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Referenc	Reference to 25 °C, I _D = 1 mA			-	V/°C
Gate-Source Threshold Voltage (N)	V _{GS(th)}	V _{DS} =	V _{DS} = V _{GS} , I _D = 250 μA			4.0	V
	I	$V_{GS} = \pm 20 V$		-	-	± 100	nA
Gate-Source Leakage	I _{GSS}		V _{GS} = ± 30 V	-	-	± 1	μA
Zara Cata Valtaga Drain Currant		V _{DS} =	$V_{DS} = 600 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$		-	1	μA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 600 V	V_{DS} = 600 V, V_{GS} = 0 V, T_{J} = 150 °C		-	100	
Drain-Source On-State Resistance	R _{DS(on)}	$V_{GS} = 10 V$			0.160	0.190	Ω
Forward Transconductance ^a	9 _{fs}	V _{DS} = 50 V, I _D = 13 A		-	9.4	-	S
Dynamic							
Input Capacitance	C _{iss}	$V_{GS} = 0 V,$		562	2810	5620	pF
Output Capacitance	C _{oss}		$V_{DS} = 25 V,$ f = 1.0 MHz		1480	2960	
Reverse Transfer Capacitance	C _{rss}				33	66	
Total Gate Charge	Qg			-	75	110	
Gate-Source Charge	Q _{gs}	$V_{GS} = 10 V$	$I_D = 22 \text{ A}, V_{DS} = 480 \text{ V}$	-	17	-	nC
Gate-Drain Charge	Q _{gd}				25	-	1
Turn-On Delay Time	t _{d(on)}	$V_{DD} = 380 \text{ V}, \text{ I}_{D} = 22 \text{ A},$ $\text{R}_{g} = 9.1 \Omega, \text{ V}_{\text{GS}} = 10 \text{ V}$		-	24	50	- ns
Rise Time	t _r			-	68	100	
Turn-Off Delay Time	t _{d(off)}			-	77	115	
Fall Time	t _f			-	59	90	
Gate Input Resistance	Rg	f = 1 MHz, open drain		0.13	0.65	1.3	Ω
Drain-Source Body Diode Characteristic	s						
Continuous Source-Drain Diode Current	I _S	showing the	MOSFET symbol showing the		-	22	А
Pulsed Diode Forward Current	I _{SM}	integral reverse p - n junction diode		-	-	65	A
Diode Forward Voltage	V _{SD}	$T_J = 25 \text{ °C}, I_S = 22 \text{ A}, V_{GS} = 0 \text{ V}$		-	-	1.2	V
Reverse Recovery Time	t _{rr}	$T_{J} = 25 \text{ °C}, I_{F} = I_{S},$ dl/dt = 100 A/µs, V _R = 25 V		-	462	-	ns
Reverse Recovery Charge	Q _{rr}			-	8.3	-	μC
Reverse Recovery Current	I _{RRM}			-	30	-	Α

Note

a. $C_{oss eff.}$ (TR) is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DS} .

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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

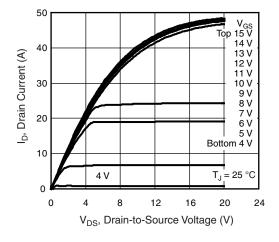


Fig. 1 - Typical Output Characteristics, T_J = 25 °C

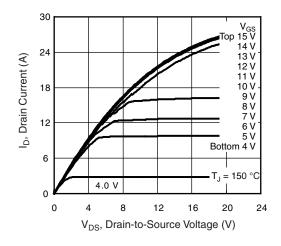


Fig. 2 - Typical Output Characteristics, T_J = 150 °C

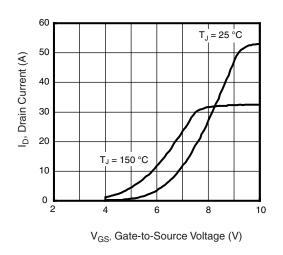


Fig. 3 - Typical Transfer Characteristics

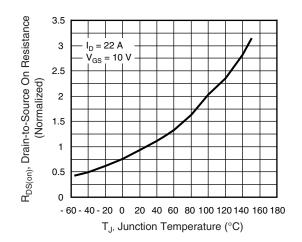


Fig. 4 - Normalized On-Resistance vs. Temperature

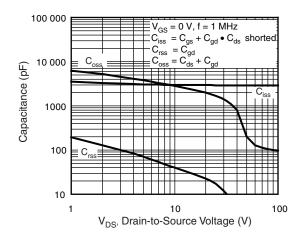


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

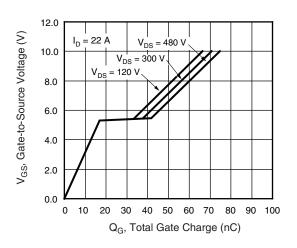


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

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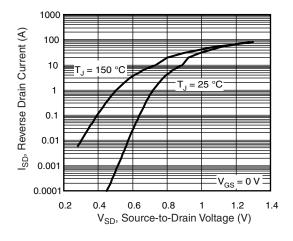
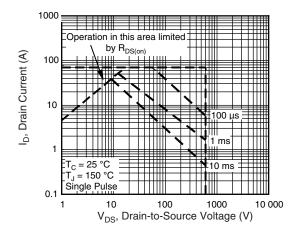


Fig. 7 - Typical Source-Drain Diode Forward Voltage





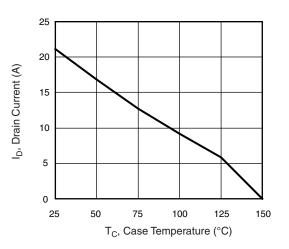


Fig. 9 - Maximum Drain Current vs. Case Temperature

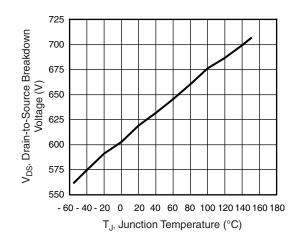


Fig. 10 - Drain-to-Source Breakdown Voltage

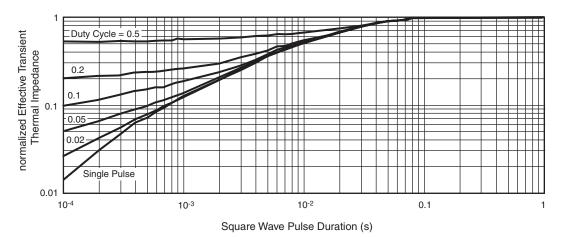


Fig. 11 - Normalized Thermal Transient Impedance, Junction-to-Case

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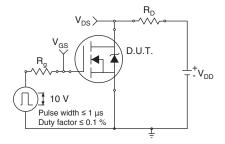


Fig. 12 - Switching Time Test Circuit

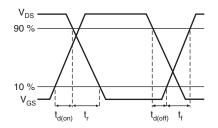


Fig. 13 - Switching Time Waveforms

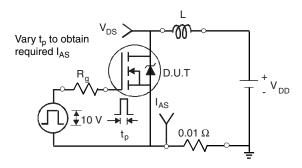


Fig. 14 - Unclamped Inductive Test Circuit

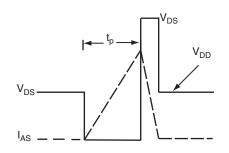


Fig. 15 - Unclamped Inductive Waveforms

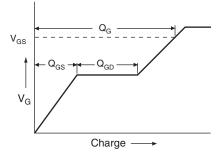


Fig. 16 - Basic Gate Charge Waveform

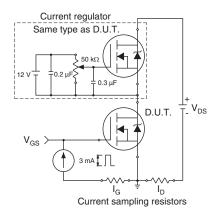
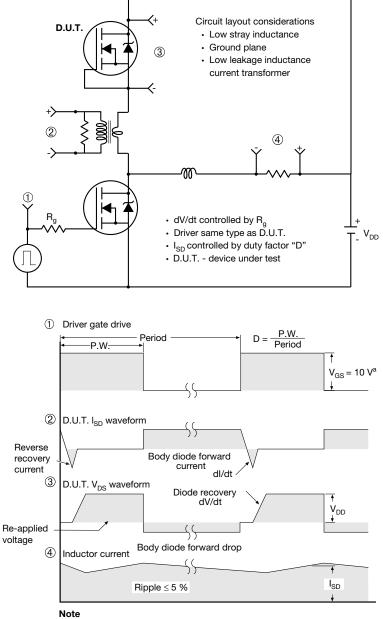


Fig. 17 - Gate Charge Test Circuit



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Peak Diode Recovery dV/dt Test Circuit



a. $V_{GS} = 5 V$ for logic level devices

Fig. 18 - For N-Channel

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